

NOTES:

1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK
 - 1.2 COVER: THERMOPLASTIC, HIGH TEMP., UL94V-0; COLOR:BLACK.
 - 1.3 CONTACT: COPPER ALLOY
2. FINISH:
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
 - L: 100u" MIN. PURE TIN OVERALL,
 - N: 100u" MIN MATT TIN PLATING OVERALL
 - C: 15U" GOLD ON CONTACT
 - 100~150u"MATT TIN ON SOLDER AREA
 - 1: GOLD FLASH ON CONTACT
 - 100~150u"MATT TIN ON SOLDER AREA
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
5. SPEC. PLS. REFER TO PS-50960-XXXXX
6. PACKAGE PLS. REFER TO 91960-XXXX-TRP

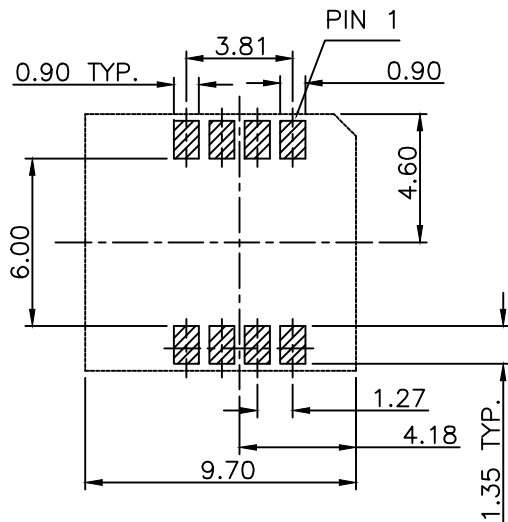
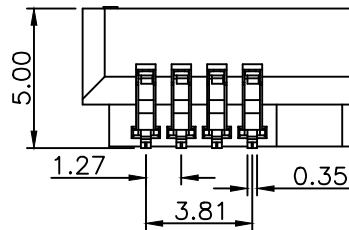
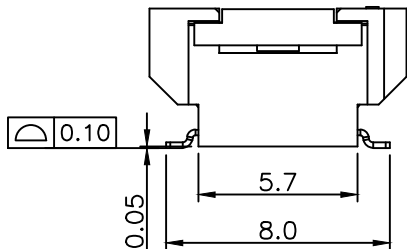
7. PART NUMBER

50960-XXX X X-XXX
 NO OF CKT 008

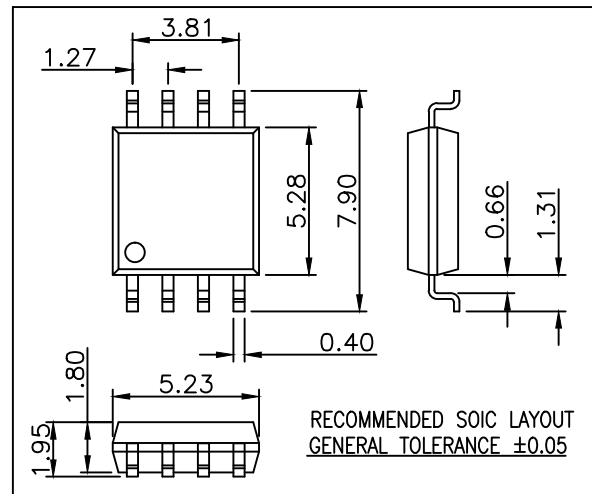
| | | |
|-----|-------|--------------|
| XXX | Color | Halogen Free |
| 001 | Black | HF |

PACKING
 0:TAPE & REEL
 4:TAPE & REEL WITH MYLAR
 5:TUBE WITH MYLAR

PLATING
 L: LEAD FREE(PURE TIN)
 N: MATT TIN(LEAD FREE)
 C: 15U" GOLD ON CONTACT
 100~150u"MATT TIN ON SOLDER AREA
 1: GOLD FLASH ON CONTACT
 100~150u"MATT TIN ON SOLDER AREA

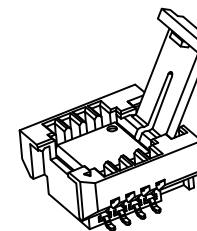
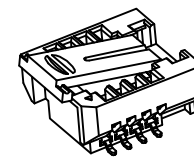
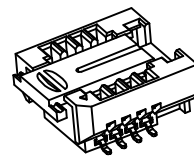
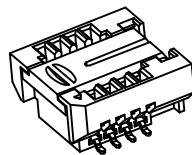
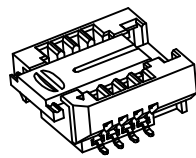
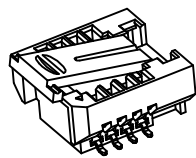
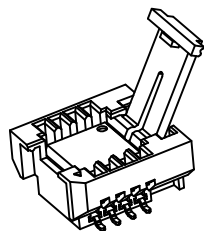


RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ± 0.05



RECOMMENDED SOIC LAYOUT
 GENERAL TOLERANCE ± 0.05

| | | | |
|--|--|---------------------|-------------------------|
| QUALITY SYMBOLS MAJOR CRITICAL | DRAWN BY Huang,Shun Sen 18/11/10 | DATE 18/11/10 | ACES ELECTRONICS |
| GENERAL TOLERANCES (UNLESS SPECIFIED) .X ± 0.5 .X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$ | CHECKED BY Lu,Jing Quan 18/11/10 | DATE 18/11/10 | |
| | APPROVED BY hsieh,fu yu 18/11/10 | DATE 18/11/10 | RFQ NO. X |
| | UNITS mm | SIZE A4 | PART NO. SEE NOTES |
| | SCALE 4:1 | SHEET NO. 1 OF 2 | REV C |
| | | | DWG NO. 50960-XXXXX-XXX |



STEP 7

STEP 6

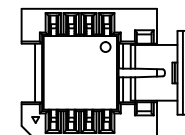
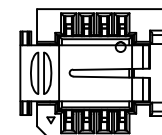
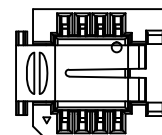
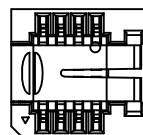
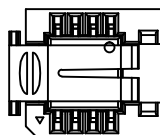
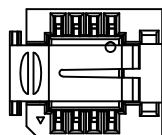
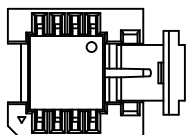
STEP 5

STEP 4

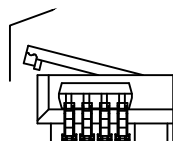
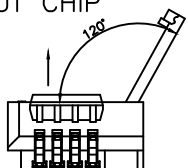
STEP 3

STEP 2

STEP 1

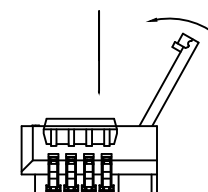
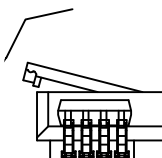
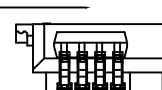
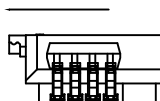


TACK OUT CHIP



COVER OPEN ANGLE 120°

COVER CLOSE



CHIP INSIDE WHEN COVER OPEN

| | | | | | |
|---|--|-------------------------------------|--|--|--|
| QUALITY SYMBOLS MAJOR CRITICAL | | DRAWN BY Huang,Shun Sen 18/11/10 | | DATE 18/11/10 | |
| GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2° | | CHECKED BY Lu,Jing Quan 18/11/10 | | DATE 18/11/10 | |
| | | APPROVED BY hsieh,fu yu 18/11/10 | | DATE 18/11/10 | |
| UNITS mm | | SIZE A4 | | TITLE 1.27mm SPI FLASH SOCKET SMT S/T TYPE | |
| SCALE 2:1 | | SHEET NO. 2 OF 2 | | REV C | |
| | | RFQ NO. X | | PART NO. SEE NOTES | |
| | | DWG NO. 50960-XXXX-XXX | | | |